CHIPQUIK® TC3-10G

Datasheet revision 1.4 www.chipquik.com

Heat Sink Compound - Grey *Ultra Max*™ Conductive 10g Syringe 5cc

Product Highlights

- **Lead-Free / RoHS 3 Compliant / REACH Compliant**
- *Ultra Max*™ High-Density Thermal Paste. Grey, non-curing, flowable, thermally conductive heat sink compound. Heavily filled with heat-conductive metal oxide. Provides extremely high thermal conductivity, low bleed and high temperature stability.
- Electrically insulating (4 x 10^{13} ohm-cm)

Specifications

Viscosity:	87,000 cP (87,000 mPa·s)
Density:	2.5g/cc
Thermal Conductivity:	8.5 W/m·K
Thermal Resistance:	0.03 °C*cm^2/W
Electrical Volume Resistivity:	4 x 10^{13} ohm-cm
Operating Temperature (Continuous):	-40 to 150°C (-40 to 302°F)
Operating Temperature (Peak):	200°C (392°F)
Operating Life:	>8 years *dependent on several factors, test in application to ensure suitability
Size:	10g Syringe (5cc)

Storage and Handling

Store refrigerated or at room temperature 3-25°C (37-77°F). Allow 4 hours for thermal paste to reach an application temperature of 20-25°C (68-77°F) before use.

Shelf Life

>24 months

Stencil Life

>7 days @ 20-70% RH 22-28°C (72-82°F)

Transportation

This product has no shipping restrictions. Shipping below 0°C (32°F) or above 25°C (77°F) for normal transit times by ground or air will not impact this product's stated shelf life.

Chip Quik® Thermal Paste Orderable Part Numbers

Thermal Conductivity (W/m·K)	Thermal Resistance (°C*cm^2/W)	Density (g/cc)	Color	Package	Size (g)	Orderable Part Number
0.67	0.16	2.1	White	Syringe	10	TC1-10G
0.67	0.16	2.1	White	Syringe	20	TC1-20G
0.67	0.16	2.1	White	Jar	200	TC1-200G
4.3	0.06	2.5	Grey	Syringe	10	TC2-10G
4.3	0.06	2.5	Grey	Syringe	20	TC2-20G
4.3	0.06	2.5	Grey	Jar	50	TC2-50G
8.5	0.03	2.5	Grey	Syringe	1	TC3-1G
8.5	0.03	2.5	Grey	Syringe	3.5	TC3-3.5G
8.5	0.03	2.5	Grey	Syringe	10	TC3-10G